Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	6
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	6.67 E-03	379609
Resin	15.0	1.22 E-03	69356
Sb2O3	1.4	1.14 E-04	6473
Brominated epoxy	1.0	8.12 E-05	4624
Carbon Black	0.6	4.06 E-05	2312
Subtotal		8.12 E-03	462374

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD
PBDE	Not Detected	Draft IEC 62321. GC-MSD

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	7.53 E-03	429006
Fe	2.35	1.76 E-04	10020
Zn	0.12	9.75 E-06	555
P	0.03	1.87 E-06	107
Subtotal		7.72 E-03	439688

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD
PBDE	Not Detected	Draft IEC 62321. GC-MSD

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.80 E-05	4442

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.02 E-04	22889

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-04	9679

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-03	56943

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3189
Resin	15	1.05 E-05	598
Aromatic Amine	5	3.50 E-06	199
Subtotal		7.00 E-05	3986

Package Totals

Weight (g)	PPM
1.76 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT 23 - FCOL
Body Size	--
LeadCount	6
Option	Sn with exemption, RoHS-compliant

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	81.0	6.56 E-03	338233
Epoxy Resin	10.0	8.10 E-04	41757
Phenol Resin	5.0	4.05 E-04	20879
Antimony Trioxide	1.4	1.13 E-04	5846
Additive	1.1	8.91 E-05	4593
Brominated epoxy	1.0	8.10 E-05	4176
Carbon Black	0.5	4.05 E-05	2088
Subtotal	100.0	8.10 E-03	417571

Molding Compound

Substance	PPM	Method
Lead	None Detected	Draft IEC 62321. ICP-OES.
Cadmium	None Detected	Draft IEC 62321. ICP-OES.
Mercury	None Detected	Draft IEC 62321. ICP-OES.
Chromium+6	None Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	None Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	None Detected	Draft IEC 62321. GC-MSD.

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	6.03 E-03	311004
Iron	2.35	1.45 E-04	7496
Zinc	0.12	7.43 E-06	383
Phosphorus	0.03	1.86 E-06	96
Subtotal	100.00	6.19 E-03	318978

External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Tin	100.0	2.34 E-04	12062

Solder Paste

Substance	% of Solder Paste	Weight (g)	PPM
Lead	75.0	3.83 E-04	19719
Indium	25.0	1.28 E-04	6573
Subtotal	100.0	5.10 E-04	26292

Wafer Bumps

Substance	% of Wafer Bumps	Weight (g)	PPM
Lead	90.0	3.02 E-04	15561
Tin	10.0	3.35 E-05	1729
Subtotal	100.0	3.35 E-04	17291

UBM

Substance	% of UBM	Weight (g)	PPM
Copper	64.16	1.28 E-06	66
Nickel	24.81	4.96 E-07	26
Vanadium	9.17	1.83 E-07	9
Aluminum	1.87	3.73 E-08	2
Subtotal	100.00	2.00 E-06	103

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100.0	4.03 E-03	207703

Package Totals

Weight (g)	PPM
1.94 E-02	1000000

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Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	6
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	6.67 E-03	379004
Resin	15.0	1.22 E-03	69245
Sb2O3	1.4	1.14 E-04	6463
Brominated epoxy	1.0	8.12 E-05	4616
Carbon Black	0.6	4.06 E-05	2308
Subtotal		8.12 E-03	461637

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	7.53 E-03	428323
Fe	2.35	1.76 E-04	10004
Zn	0.12	9.75 E-06	554
P	0.03	1.87 E-06	106
Subtotal		7.72 E-03	438987

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.80 E-05	4434

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.66 E-04	20779
Pb	15	6.45 E-05	3667
Subtotal		4.30 E-04	24446

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-04	9664

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-03	56852

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3184
Resin	15	1.05 E-05	597
Aromatic Amine	5	3.50 E-06	199
Subtotal		7.00 E-05	3980

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD
PBDE	Not Detected	Draft IEC 62321. GC-MSD

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD
PBDE	Not Detected	Draft IEC 62321. GC-MSD

Package Totals

Weight (g)	PPM
1.76 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT23-COL
Body Size	
LeadCount	6
Option	NiPdAu

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	80.8	6.56 E-03	382346
Epoxy resin	9.0	7.31 E-04	42588
Phenol Resin	5.0	4.06 E-04	23660
Metal Hyroxide	5.0	4.06 E-04	23660
Carbon Black	0.2	1.62 E-05	946
Subtotal	100.0	8.12 E-03	473201

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	7.51 E-03	437856
Iron	2.35	1.76 E-04	10255
Zinc	0.12	9.75 E-06	568
Phosphorus	0.03	1.87 E-06	109
Subtotal	100	7.70 E-03	448788

Internal/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	8.97 E-05	5227
Palladium	7.91	7.80 E-06	455
Gold	1.19	1.17 E-06	68
Subtotal	100.00	9.87 E-05	5750

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	1.70 E-04	9906

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	1.00 E-03	58276

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	2.17 E-05	1265
Metal Oxide	31	2.17 E-05	1265
Glycol Ethers	22	1.54 E-05	897
Silica	8	5.60 E-06	326
Curing agent & hardener	8	5.60 E-06	326
Subtotal	100	7.00 E-05	4079

Molding Compound

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES
Cadmium	Not Detected	Draft IEC 62321. ICP-OES
Mercury	Not Detected	Draft IEC 62321. ICP-OES
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES
Cadmium	Not Detected	Draft IEC 62321. ICP-OES
Mercury	Not Detected	Draft IEC 62321. ICP-OES
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
1.72 E-02	1000000

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